L Number	Hits	Search Text	DB	Time stamp
-	1	(knife adj ring) near (movable or moveable or positionable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:02
-	204	knife adj ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:59
-	0	(("15156.DID.").PN.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:00
-	9	(knife adj ring) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:03
-	233	134/149.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:03
-	46	134/149.ccls. and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:16
-	650	134/184.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:16
-	212	134/184.ccls. and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:24
-	717	134/186.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:24
-	151	134/186.ccls. and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:24
-	9	(134/186.ccls. and (wafer or semiconductor)) and knife	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:25
-	5	(air adj knife) near (movable or moveable or positionable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:03
-	134	(air adj knife) same (movable or moveable or positionable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:11
-	1540045	wafer or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:12

-	20	((air adj knife) same (movable or moveable or positionable)) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:14
-	296	134/148.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:14
-	65	134/148.ccls. and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:30
-	797	134/153.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:30
-	6	(134/153.ccls. and (wafer or semiconductor)) and (air same ((backside or underside) near wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:31
-	291	134/153.ccls. and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 10:43
-	171	134/154.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:38
-	2190	134/902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:38
-	37	134/902.ccls. and (air adj knife)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:48
-	0	air adj ((nozzle or jet or knife) same (wafer near backside))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:49
-	11	air same ((nozzle or jet or knife) same (wafer near backside))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:53
-	9711	"taiwan semiconductor".as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:54
-	3	"taiwan semiconductor".as. and (knife same ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:55
-	1540045	wafer or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 12:04

-	1540045	wafer or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:23
-	236056	(knife adj edge) or (knife adj ring) or divider	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:24
-	11653	((knife adj edge) or (knife adj ring) or divider) same (backside or rear or (back adj side) or reverse)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:25
-	1755225	((knife adj edge) or (knife adj ring) or divider) same (backside or rear or (back adj side) or reverse) near[25] (adjustable or movable or moveable or positionable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:26
-	1265	(wafer or semiconductor) and (((knife adj edge) or (knife adj ring) or divider) same (backside or rear or (back adj side) or reverse))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:27
-	5	((wafer or semiconductor) and (((knife adj edge) or (knife adj ring) or divider) same (backside or rear or (back adj side) or reverse))) and 134/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:27